

Abstract of the Disclosure

An adhesive tape for the removal of a resist includes a curing adhesive layer having an initial tensile modulus of not smaller than 10 MPa at 100°C after cured provided on a supporting base material, and/or an adhesive layer provided on a supporting base material having a flexural stiffness of not smaller than 1×10^{-4} (N·m) per unit width.

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